
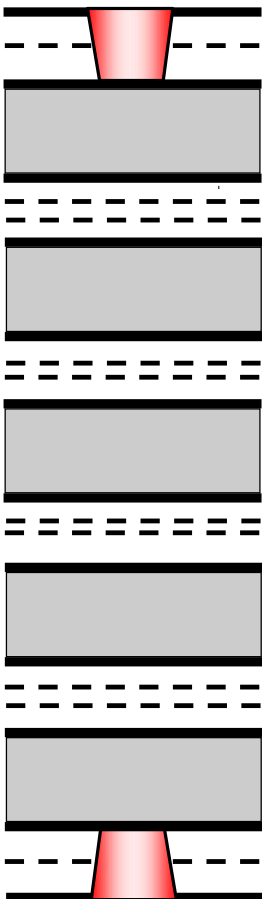


Build Up HDI (Standard)											
HDI12_1+10+1_1,35_17.5_engl			12 - Layers Core: 0,10 mm Cu 17.5/17.5 µm								
WE-Article No.:		1 + 10 + 1									
Customer:											
layer description		configuration			Raw-Material	CU	PREPREG	Final Thickness	Customer requirements		
Customer	WE							[µm]	[µm]		
	TOP/VS				Foil	12 µm ¹⁾		12			
									1 x 1080	66	
	2						0,100 mm	17,5 µm		16	
	3							17,5 µm		16	
									2 x 1080	134	
	4							17,5 µm		16	
							0,100 mm			100	
	5							17,5 µm		16	
									2 x 1080	134	
	6							17,5 µm		16	
				0,100 mm			100				
	7				17,5 µm		16				
						2 x 1080	134				
	8				17,5 µm		16				
				0,100 mm			100				
	9				17,5 µm		16				
						2 x 1080	134				
	10				17,5 µm		16				
				0,100 mm			100				
	11				17,5 µm		16				
						1 x 1080	66				
	BOT/RS			Foil	12 µm ¹⁾		12				
					1) copper thickness outer layers: appr. 55 µm						
					total material thickness: 1352 Note: Lamination thickness for Prepregs depending on layout characteristics.						

final lamination thickness:	1,35	+/-	0,11	mm	Date:	Engineer:
thickness with electro plated Cu:	1,44	+/-	0,14	mm		
total thickness with soldermask	1,50	+/-	0,16	mm		
customer requirement		+/-		mm	point:	

prepared:	checked:	approved:	revision
on 28.03.2006 by S. Keller	on 04.05.2006 by M.Kress	on 04.05.2006 by R. Schönholz	00
			page: 4+